

74 may be coated or printed on the metallic ground layer 71 as shown in Fig. 15. At this time, multiple circular pads 75 are formed in the high dielectric value material 74, thereby exposing the metallic ground layer 71 not coated or printed with the high dielectric value material 74. Then, the high dielectric value material 74 is covered with metallic paste or high conductive material that may be filled into the circular pads 75, thereby forming a planar jumper layer 76 (as shown in Fig. 16) that is connected to the metallic ground layer 71 through the circular pads 75.--

Please amend the entire paragraph beginning at page 14, line 1, as shown in the following Clean Version, a Marked-Up Version of which is attached to this Amendment:

--Referring to Figs. 17-19, the same method in accordance with the present invention may be used make another type coplanar waveguide of a microwave circuit of a printed circuit board. After the metallic ground layer 61 is mounted on the bottom side of the dielectric substrate 62 as shown in Fig. 17, a high dielectric value material 64 may be coated or printed on the metallic ground layer 61 as shown in Fig. 18. At this time, multiple circular pads 65 are formed in the high dielectric value material 64, thereby exposing the metallic ground layer 61 not coated or printed with the high dielectric value material 64. Then, the high dielectric value material 64 is covered with metallic paste or high conductive material that may be filled into the circular pads 65, thereby forming a planar jumper layer 66 (shown in Fig. 19) that is connected to the metallic ground layer 61 through the circular pads 65.--